

## Features:

- Isolated mounting base 2500V~
- Simple design, Module and SCR rectifier bridge, Small volume, light weight

## Typical Applications:

- Supplies for DC power equipment
- Field supply for DC motors
- Inverter welder

$V_{DSM}, V_{RSM}$	$V_{DRM}, V_{RRM}$	Type
900V	800V	MG150TH80S
1100V	1000V	MG150TH100S
1300V	1200V	MG150TH120S
1500V	1400V	MG150TH140S
1700V	1600V	MG150TH160S
1900V	1800V	MG150TH180S

## Diode

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	$T_j(^{\circ}C)$	VALUE			UNIT
				Min	Type	Max	
$I_D$	DC output current	Three-phase full wave rectifying circuit, $T_c=100^{\circ}C$	125			150	A
$V_{RRM}$	Repetitive peak reverse voltage	$t_p=10ms$	125	600		1800	V
$I_{RRM}$	Repetitive peak current	at $V_{RRM}$	125			8	mA
$I_{FSM}$	Surge forward current	10ms half sine wave $V_R=0$	125			1.3	kA
$I^{2t}$	$I^{2t}$ for fusing coordination					8.45	$A^2s*10^3$
$V_{FO}$	Threshold voltage		125			0.85	V
$r_F$	Forward slope resistance					1.60	$m\Omega$
$V_{FM}$	Peak forward voltage	$I_{FM}=150A$	25			1.40	V
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled, per chip				0.15	$^{\circ}C /W$
$R_{th(c-h)}$	Thermal resistance case to heatsink	Single side cooled, per chip				0.07	$^{\circ}C /W$
$V_{iso}$	Isolation voltage	50Hz,R.M.S., $t=1min$ , $I_{iso}=1mA$ (max)		2500			V
$F_m$	Terminal connection torque(M6)				6		$N\cdot m$
	Mounting torque(M6)				6		$N\cdot m$
$T_{stg}$	Stored temperature			-40		125	$^{\circ}C$
$W_t$	Weight				280		g
Outline	M33						

## Thyristor

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T <sub>j</sub> (°C)	VALUE			UNIT
				Min	Type	Max	
I <sub>T(AV)</sub>	Mean on-state current	180° half sine wave 50Hz Single side cooled, T <sub>c</sub> =100°C	125			150	A
V <sub>DRM</sub> V <sub>RRM</sub>	Repetitive peak off-state voltage Repetitive peak reverse voltage	tp=10ms	125	600		1800	V
I <sub>DRM</sub> I <sub>RRM</sub>	Repetitive peak current	at V <sub>DRM</sub> at V <sub>RRM</sub>	125			40	mA
I <sub>TSM</sub>	Surge on-state current	10ms half sine wave V <sub>R</sub> =60%V <sub>RRM</sub>	125			1.3	mA
I <sup>2</sup> t	I <sup>2</sup> t for fusing coordination					8.45	A <sup>2</sup> s*10 <sup>3</sup>
V <sub>TO</sub>	Threshold voltage	V <sub>A</sub> =12V, I <sub>A</sub> =1A	125			0.85	V
r <sub>T</sub>	On-state slop resistance					1.6	mΩ
I <sub>GT</sub>	Gate trigger current			30		200	mA
V <sub>GT</sub>	Gate trigger voltage	V <sub>A</sub> =12V, I <sub>A</sub> =1A	25	0.6		2.5	V
I <sub>H</sub>	Holding current			10		250	mA
V <sub>TM</sub>	Peak on-state voltage	I <sub>TM</sub> =450A				1.65	V
dv/dt	Critical rate of rise of off-state voltage	V <sub>DM</sub> =67%V <sub>DRM</sub>	125			500	V/μs
R <sub>th(j-c)</sub>	Thermal resistance Junction to case	Single side cooled, per chip				0.20	°C/W
R <sub>th(c-h)</sub>	Thermal resistance case to heatsink	Single side cooled, per chip				0.10	°C/W
V <sub>iso</sub>	Isolation voltage	50Hz, R.M.S,t=1min, I <sub>iso</sub> :1mA(MAX)		2500			V
F <sub>m</sub>	Terminal connection torque(M6)				6		N·m
	Terminal connection torque(M4)				2.5		N·m
	Mounting torque(M6)				6		N·m
T <sub>stg</sub>	Stored temperature			-40		125	°C
W <sub>t</sub>	Weight				280		g
Outline		M33					

**Outline:**